

L Number	Hits	Search Text	DB	Time stamp
-	283	(324/229.cccls.) and @ad>20030207	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/07/14 15:40
-	1169	(324/228,200.cccls.) and @ad>20030207	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/07/19 12:22
-	160	(324/600,629.cccls.) and @ad>20030207	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/07/14 15:41
-	158	(324/633,635.cccls.) and @ad>20030207	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/07/14 15:41
-	756	(324/663,662.cccls.) and @ad>20030207	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/07/14 15:42
-	135	(324/668,652.cccls.) and @ad>20030207	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/07/14 15:42
-	510	(324/658,654.cccls.) and @ad>20030207	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/07/14 15:46
42		((324/228,200.cccls.) and @ad>20030207) and rota\$7 near2 (table bin holder receptacle container box case shell tray frame structure form fabric shape manner way trend enclose base infrastructure chassis housing framework shell floor plate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/14 15:47
44		((324/663,662.cccls.) and @ad>20030207) and rota\$7 near2 (table bin holder receptacle container box case shell tray frame structure form fabric shape manner way trend enclose base infrastructure chassis housing framework shell floor plate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/14 15:47

-	16	((324/229.ccls.) and @ad<20030207) and rota\$7 near2 (table bin holder receptacle container box case shell tray frame structure form fabric shape manner way trend enclose base infrastructure chassis housing framework shell floor plate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/14 15:48
-	4	((324/600,629.ccls.) and @ad<20030207) and rota\$7 near2 (table bin holder receptacle container box case shell tray frame structure form fabric shape manner way trend enclose base infrastructure chassis housing framework shell floor plate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/14 16:14
-	9	((324/633,635.ccls.) and @ad<20030207) and rota\$7 near2 (table bin holder receptacle container box case shell tray frame structure form fabric shape manner way trend enclose base infrastructure chassis housing framework shell floor plate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/14 16:15
-	6	((324/668,652.ccls.) and @ad<20030207) and rota\$7 near2 (table bin holder receptacle container box case shell tray frame structure form fabric shape manner way trend enclose base infrastructure chassis housing framework shell floor plate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/14 16:41
-	12	((324/658,654.ccls.) and @ad<20030207) and rota\$7 near2 (table bin holder receptacle container box case shell tray frame structure form fabric shape manner way trend enclose base infrastructure chassis housing framework shell floor plate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/14 16:29
-	2	((((324/228,200.ccls.) and @ad<20030207) and rota\$7 near2 (table bin holder receptacle container box case shell tray frame structure form fabric shape manner way trend enclose base infrastructure chassis housing framework shell floor plate)) and (substrate material \$5film coat\$3 layer sheet pad wafer subject object) near2 (manufact\$7 treatment))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/14 16:31
-	8	((((324/663,662.ccls.) and @ad<20030207) and rota\$7 near2 (table bin holder receptacle container box case shell tray frame structure form fabric shape manner way trend enclose base infrastructure chassis housing framework shell floor plate)) and (substrate material \$5film coat\$3 layer sheet pad wafer subject object) near2 (manufact\$7 treatment))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/14 16:39
-	10	((324/229.ccls.) and @ad<20030207) and (substrate material \$5film coat\$3 layer sheet pad wafer subject object) near2 (manufact\$7 treatment)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/14 16:39
-	16	((324/228,200.ccls.) and @ad<20030207) and (substrate material \$5film coat\$3 layer sheet pad wafer subject object) near2 (manufact\$7 treatment)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/14 16:39

-	13	((324/600.629.ccIs.) and @ad>20030207) and (substrate material \$5film coat\$3 layer sheet pad wafer subject object) near2 (manufact\$7 treatment)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/14 16:39
-	10	((324/633.635.ccIs.) and @ad>20030207) and (substrate material \$5film coat\$3 layer sheet pad wafer subject object) near2 (manufact\$7 treatment)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/14 16:40
-	45	((324/663.662.ccIs.) and @ad>20030207) and (substrate material \$5film coat\$3 layer sheet pad wafer subject object) near2 (manufact\$7 treatment)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/14 16:40
-	2	((324/668.652.ccIs.) and @ad>20030207) and (substrate material \$5film coat\$3 layer sheet pad wafer subject object) near2 (manufact\$7 treatment)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/14 16:40
-	12	((324/658.654.ccIs.) and @ad>20030207) and (substrate material \$5film coat\$3 layer sheet pad wafer subject object) near2 (manufact\$7 treatment)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/14 16:55
-	1	((((324/229.ccIs.) and @ad>20030207) and (substrate material \$5film coat\$3 layer sheet pad wafer subject object) near2 (manufact\$7 treatment)) and rota\$7 near2 (table bin holder receptacle container box case shell tray frame structure form fabric shape manner way trend enclose base infrastructure chassis housing framework shell floor plate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/14 16:47
-	2	((((324/228.200.ccIs.) and @ad>20030207) and (substrate material \$5film coat\$3 layer sheet pad wafer subject object) near2 (manufact\$7 treatment)) and rota\$7 near2 (table bin holder receptacle container box case shell tray frame structure form fabric shape manner way trend enclose base infrastructure chassis housing framework shell floor plate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/14 16:47
-	1	((((324/633.635.ccIs.) and @ad>20030207) and (substrate material \$5film coat\$3 layer sheet pad wafer subject object) near2 (manufact\$7 treatment)) and rota\$7 near2 (table bin holder receptacle container box case shell tray frame structure form fabric shape manner way trend enclose base infrastructure chassis housing framework shell floor plate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/14 16:49
-	8	((((324/663.662.ccIs.) and @ad>20030207) and (substrate material \$5film coat\$3 layer sheet pad wafer subject object) near2 (manufact\$7 treatment)) and rota\$7 near2 (table bin holder receptacle container box case shell tray frame structure form fabric shape manner way trend enclose base infrastructure chassis housing framework shell floor plate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/14 16:56

-	99390	((pad wafer subject object) near2 (manufact\$7 treatment)) and @ad<20030207	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/07/15 12:00
-	1404	((pad wafer subject object) near2 (manufact\$7 treatment)) and @ad>20030207) and (rota\$7 near2 (table bin holder receptacle container box case shell tray frame structure form fabric shape manner way trend enclose base infrastructure chassis housing framework shell floor plate dis\$1)) near5 (pad wafer subject object)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/07/15 12:04
-	35	((((pad wafer subject object) near2 (manufact\$7 treatment)) and @ad<20030207) and (rota\$7 near2 (table bin holder receptacle container box case shell tray frame structure form fabric shape manner way trend enclose base infrastructure chassis housing framework shell floor plate dis\$1)) near5 (pad wafer subject object)) and (sens\$3 detect\$3) near5 (carriage carrier means)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/07/15 12:03
-	700	(324/230,262.cc1s.) and @ad<20030207	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/07/15 11:53
-	852	(324/758,759.cc1s.) and @ad<20030207	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/07/15 11:53
-	2115	(451/5,8,9,10.cc1s.) and @ad<20030207	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/07/15 11:56
-	1040	(356/138,141.2.cc1s.) and @ad>20030207	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/07/15 12:58
-	4034	(438/10,13,17.cc1s.) and @ad<20030207	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/07/15 11:58
-	797	(29/593.cc1s.) and @ad>20030207	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/15 11:58

-	150	((451/5,8,9,10.cccls.) and @ad>20030207) and ((pad wafer subject object substrate) near2 (manufact\$7 treatment))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/15 12:01
-	212	((438/10,13,17.cccls.) and @ad<20030207) and ((pad wafer subject object substrate) near2 (manufact\$7 treatment))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/15 12:02
-	997	(356/73,485,496.cccls.) and @ad<20030207	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/15 15:03
-	519	(702/34,35,36.cccls.) and @ad>20030207	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/15 12:58
-	2319	(356/399,400,486,614,622.cccls.) and @ad>20030207	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/15 15:06
-	8	((324/230,262.cccls.) and @ad<20030207) and ((pad wafer subject object substrate) near2 (manufact\$7 treatment))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/15 15:07
-	6	((356/138,141,2.cccls.) and @ad>20030207) and ((pad wafer subject object substrate) near2 (manufact\$7 treatment))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/15 16:11
-	13	((451/5,8,9,10.cccls.) and @ad>20030207) and ((pad wafer subject object substrate) near2 (manufact\$7 treatment)) and (sens\$3 detect\$3) near5 (carriage carrier means)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/15 15:12
-	6	((438/10,13,17.cccls.) and @ad>20030207) and ((pad wafer subject object substrate) near2 (manufact\$7 treatment)) and (sens\$3 detect\$3) near5 (carriage carrier means)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/15 15:30

-	3	((((451/5,8,9,10.cccls.) and @ad<20030207) and ((pad wafer subject object substrate) near2 (manufact\$7 treatment))) and (rota\$7 near2 (table bin holder receptacle container box case shell tray frame structure form fabric shape manner way trend enclose base infrastructure chassis housing framework shell floor plate dis\$1)) near5 (pad wafer subject object) and (sens\$3 detect\$3) near5 (carriage carrier means)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/19 12:27
-	8	((356/399,400,486,614,622.cccls.) and @ad<20030207) and (sens\$3 detect\$3) near5 (carriage carrier means)) and (rota\$7 near2 (table bin holder receptacle container box case shell tray frame structure form fabric shape manner way trend enclose base infrastructure chassis housing framework shell floor plate dis\$1)) near5 (pad wafer subject object)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/15 15:40
-	44	((324/758,759.cccls.) and @ad<20030207) and ((pad wafer subject object substrate) near2 (manufact\$7 treatment))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/15 16:11
-	42	((29/593.cccls.) and @ad<20030207) and ((pad wafer subject object substrate) near2 (manufact\$7 treatment))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/15 16:13
-	41	((((451/5,8,9,10.cccls.) and @ad<20030207) and ((pad wafer subject object substrate) near2 (manufact\$7 treatment))) and (rota\$7 near2 (table bin holder receptacle container box case shell tray frame structure form fabric shape manner way trend enclose base infrastructure chassis housing framework shell floor plate dis\$1)) near5 (pad wafer subject object))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/15 16:14
-	44	((356/73,485,496.cccls.) and @ad<20030207) and (sens\$3 detect\$3) near5 (carriage carrier means)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/15 16:15
-	29	((702/34,35,36.cccls.) and @ad<20030207) and (sens\$3 detect\$3) near5 (carriage carrier means)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/15 16:16
-	91	((356/399,400,486,614,622.cccls.) and @ad<20030207) and (sens\$3 detect\$3) near5 (carriage carrier means)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/15 16:17
-	7423	(324/158,1,765.cccls.) and @ad<20030207	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/19 13:19

-	3	((324/158.1,765.cccls.) and @ad<20030207) and (pad wafer subject object substrate) near2 (manufact\$7 treatment)) and (rota\$7 near2 (table bin holder receptacle container box case shell tray frame structure form fabric shape manner way trend enclose base infrastructure chassis housing framework shell floor plate dis\$1)) near5 (pad wafer subject object)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2004/07/19 13:10
-	10	((324/158.1,765.cccls.) and @ad<20030207) and (pad wafer subject object substrate) near2 (manufact\$7 treatment)) and (sens\$3 detect\$3) near5 (carriage carrier means)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2004/07/19 13:13
-	261	((324/158.1,765.cccls.) and @ad<20030207) and (pad wafer subject object substrate) near2 (manufact\$7 treatment)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2004/07/19 13:10
-	1813	(438/692.cccls.) and @ad<20030207)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2004/07/19 13:09
-	339	((438/692.cccls.) and @ad<20030207) and (pad wafer subject object substrate) near2 (manufact\$7 treatment)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2004/07/19 13:37
-	98	((438/692.cccls.) and @ad<20030207) and (pad wafer subject object substrate) near2 (manufact\$7 treatment)) and (rota\$7 near2 (table bin holder receptacle container box case shell tray frame structure form fabric shape manner way trend enclose base infrastructure chassis housing framework shell floor plate dis\$1)) near5 (pad wafer subject object)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2004/07/19 13:37
-	3	((((438/692.cccls.) and @ad<20030207) and (pad wafer subject object substrate) near2 (manufact\$7 treatment)) and (rota\$7 near2 (table bin holder receptacle container box case shell tray frame structure form fabric shape manner way trend enclose base infrastructure chassis housing framework shell floor plate dis\$1)) near5 (pad wafer subject object)) and (sens\$3 detect\$3) near5 (carriage carrier means)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2004/07/19 13:40
-	1392	(451/65,287.cccls.) and @ad<20030207	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2004/07/19 14:18
-	842	(250/548.cccls.) and @ad<20030207	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/19 13:37

-	101	((250/548.cc1s.) and @ad<20030207) and (pad wafer subject object substrate) near2 (manufact\$7 treatment)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/19 13:37
-	169	((451/65,287.cc1s.) and @ad<20030207) and (pad wafer subject object substrate) near2 (manufact\$7 treatment)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/19 13:37
-	53	((451/65,287.cc1s.) and @ad<20030207) and (pad wafer subject object substrate) near2 (manufact\$7 treatment)) and (rota\$7 near2 (table bin holder receptacle container box case shell tray frame structure form fabric shape manner way trend enclose base infrastructure chassis housing framework shell floor plate dis\$1)) near5 (pad wafer subject object)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/19 13:38
-	4	((250/548.cc1s.) and @ad<20030207) and (pad wafer subject object substrate) near2 (manufact\$7 treatment)) and (rota\$7 near2 (table bin holder receptacle container box case shell tray frame structure form fabric shape manner way trend enclose base infrastructure chassis housing framework shell floor plate dis\$1)) near5 (pad wafer subject object)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/19 13:39
-	3	((451/65,287.cc1s.) and @ad<20030207) and (pad wafer subject object substrate) near2 (manufact\$7 treatment)) and (rota\$7 near2 (table bin holder receptacle container box case shell tray frame structure form fabric shape manner way trend enclose base infrastructure chassis housing framework shell floor plate dis\$1)) near5 (pad wafer subject object) and (sens\$3 detect\$3) near5 (carriage carrier means)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/19 13:40
-	4	("6473664" or ("6593738")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/19 14:19